

COMPETITIVE ADVANTAGES

- **A μm pattern precision** is reached by UV lithography;
- **Homogeneous surface** of the final product;
- **Lower reject rate** during manufacturing;
- **Lower manufacturing costs**;
- **Usual microelectronic equipment** (rigid substrate) is used for a flexible substrate application.

APPLICATIONS/MARKETS

- Microelectronics on flexible substrate;
- Microtechnologies, for example: Flexible sensors of deformation, stress, curvature, vibration...
- LED and OLED on a flexible substrate.

INTELLECTUAL PROPERTY

- Secret expertise.

LABORATORY

- Institut Jean Lamour

CONTACT

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PRESENTATION

This new method of temporal rigidification of flexible films enables their structuration, metallization, layer deposit by centrifugal coating, bathing, printing (...), to modify the substrate's surface. This flexible film structuration can be performed homogeneously on large surfaces.

